

CCD1600A Full Frame CCD Image Sensor 10560 x 10560 Element Image Area

General Description

The CCD1600 is a 10560 x 10560 image element solid state Charge Coupled Device (CCD) Full Frame sensor.

This CCD is intended for use in high-resolution scientific, space based, industrial, and commercial electro-optical systems.

The CCD1600 is organized in two halves each containing an array of 10560 horizontal by 5280 vertical photosites. The pixel spacing is $9\mu m \times 9\mu m$. For dark reference, each readout line is proceeded by 8 dark pixels.

This imager is available in a full frame transfer configuration (shown) or a split frame transfer configuration with shield metalization covering half of the imager. The split frame transfer architecture allows higher frame rate operation through four readout quadrants, whereas the single-sided approach allows readout through two readout quadrants.

The CCD1600 is offered as a backside illuminated version for increased sensitivity and UV response in the same package configuration.

Features

- 10560 x 10560 Photosite Full Frame CCD Array
- 9 μm x 9 μm Pixel
- 95.04mm x 95.04mm Image Area
- 100% Fill Factor
- Readout Noise Less Than 20 Electrons at 10MHz
- Dynamic Range > 75dB
- 16 Two Stage Source Follower Output Channels
- Three-Phase Buried Channel NMOS Image area
- Three-Phase Buried Channel Readout Registers
- Multi-Pinned Phase (MPP) optional

Functional Description

The following functional elements are illustrated in the block diagram:

Image Sensing Elements: Incident photons pass through a transparent polycrystalline silicon gate structure creating electron hole pairs. The resulting photoelectrons are collected in the photosites during the integration period. The amount of charge accumulated in each photosite is a linear function of the localized incident illumination intensity and integration period.

The photosite structure is made up of contiguous CCD elements with no voids or inactive areas. In addition to sensing light, these elements are used to shift image data vertically. Consequently, the device needs to be shuttered during readout.

Vertical Charge Shifting: The Full Frame architecture of the CCD1600 provides video information as a single sequential readout of 5280 lines containing 1320 photosites. At the end of an integration period the ϕA_1 , ϕA_2 , and ϕA_3 clocks are used to transfer charge vertically through the CCD array to the horizontal readout register. Vertical columns are separated by a channel stop region to prevent charge migration.

The imaging area is divided into an Upper and Lower half. Each 10560 x 5280 halve may be clocked independently or together. Horizontal Transport registers along the top and bottom permit simultaneous readout of both halves. The CCD1600 may be clocked such that the full array is readout by the Upper or Lower Transport registers.

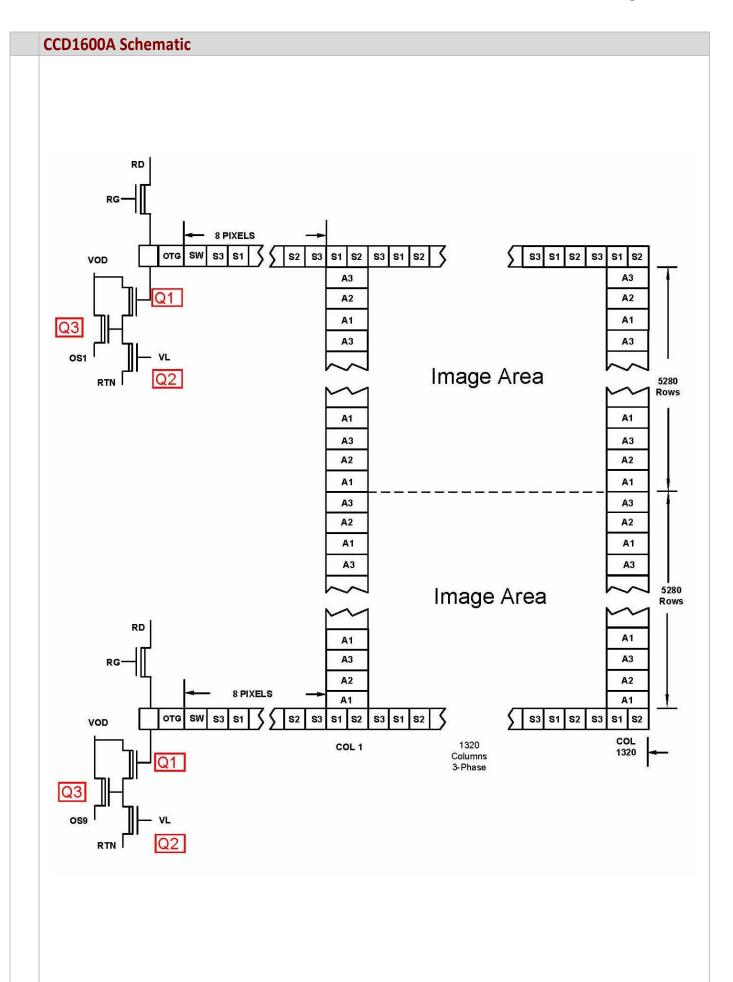
Horizontal Charge Shifting: ϕS_1 , ϕS_2 and ϕS_3 are polysilicon gates used to transfer charge horizontally to the output amplifier. The horizontal transport register is twice the size of the photosite to allow for vertical binning. For both frame transfer configurations, the charge may be read out through the eight amplifiers at the bottom or top of the image frame storage region.

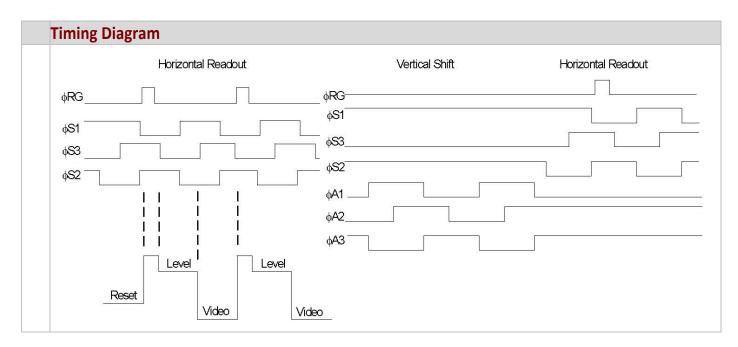
The transfer of charge into the horizontal register is the result of a vertical shift sequence. This register has 8 additional register cells between the first pixel of each line and the output amplifier. The output from these locations contains no signal and may be used as a dark level reference.

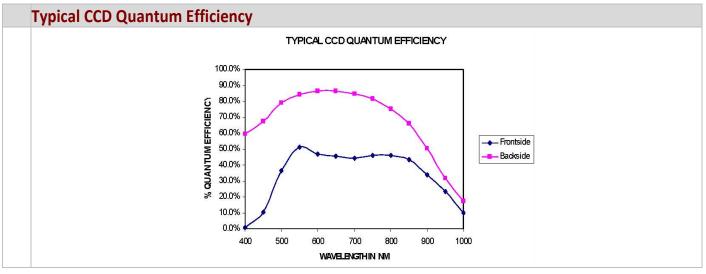
The last clocked gate in the Horizontal registers is twice as large as the others and can be used to horizontally bin charge. This gate requires its own clock, which may be tied to ϕH_2 for normal full resolution readout. The reset FET in the horizontal readout, clocked appropriately with ϕR , allows binning of adjacent pixels.

Output Amplifier: The CCD1600 has one output amplifier at the end of each Horizontal register. These are dual FET floating diffusion amplifiers with a reset MOSFET tied to the input gate.

Charge packets are clocked to a pre-charged capacitor whose potential changes linearly in response to the number of electrons delivered. When this potential is applied to the input gate of an NMOS amplifier, a signal at the output V_{out} pin is produced. The capacitor is then reset via the reset MOSFET with ϕ RG to a pre-charge level prior to the arrival of the next charge packet except when horizontally binning. The output amplifier drain is tied to VDD. The source is connected to an external load resistor to ground and constitutes the video output from the device.







Definition of Terms

Charge-Coupled Device A charge-coupled device is a monolithic silicon structure in which discrete packets of electron charge are transported from position to position by sequential clocking of an array of gates.

Vertical Transport Clocks ϕA_1 , ϕA_2 , ϕA_3 the clock signals applied to the vertical transport register.

Horizontal Transport Clocks ϕS_1 , ϕS_2 , ϕS_3 the clock signals applied to the horizontal transport registers.

Reset Clock ϕ **RG** the clock applied to the reset switch of the output amplifier.

Dynamic Range The ratio of saturation output voltage to RMS noise in the dark. The peak-to-peak random noise is 4-6 times the RMS noise output.

Saturation Exposure The minimum exposure level that produces an output signal corresponding to the maximum photosite charge capacity. Exposure is equal to the product of light intensity and integration time.

Responsivity The output signal voltage per unit of exposure.

Spectral Response Range The spectral band over which the response per unit of radiant power is more than 10% of the peak response.

Photo-Response Non-Uniformity The difference of the response levels between the most and the least sensitive regions under uniform illumination (excluding blemished elements) expressed as a percentage of the average response.

Dark Signal The output signal is caused by thermally generated electrons. Dark signal is a linear function of integration time and an exponential function of chip temperature.

Pixel Picture element or sensor element, also called photo element or photosite

DC Oper	ating Characteristics					
Symbol	Parameter	min	Range nom	max	Unit	Remarks
V _{OD}	DC Supply Voltage		+25.0	max	V	
V _{RD}	Reset Drain Voltage		16.0		V	
V _{OTG}	Output Voltage	-2.0	1.0	2.0	V	
V_{VLD}	Output Load Voltage		+3.0		V	
V _{RTN}	Output Return Voltage		+2.0		V	
V _{SC}	Scupper Voltage		+20.0		V	
V _{SUB}	Substrate Ground		0.0		V	

Typical Clock Voltages					
Symbol	Parameter	High	Low	Unit	Remarks
Vφ _{S(1,2,3)}	Horizontal Multiplexer Clock	+5.0	-5.0	V	Note 1
Vφ _{sw}	Summing Gate Clock	+5.0	-5.0	V	Note 1
Vφ _{V(1,2,3)}	Vertical Array Clocks	+3.0	-10.0	V	Note 1
$V \varphi_{RG}$	Reset Array Clock	+5.0	-5.0	V	Note 1

Note 1: ϕ H = 200pF, ϕ V = 15,000pF. All clock rise and fall times should be > 10 ns.

AC Characteristics						
Standard test conditions are nominal MPP clocks and DC operating Voltages, 1 MHz Horizontal Data Rate, 6µSec Vertical shift cycle.						
Symbol	Parameter	Range min nom max		max	Jnit	Remarks
V _{ODC}	Output DC Level		16.0		V	
Z	Suggested Load Register	1.0	5.0	20.0	kΩ	

Perform	nance Specifications					
Symbol	Parameter	min	Range nom	max	Unit	Remarks
V _{SAT}	Saturation Output Voltage Full Well Capacity Output Amp Sensitivity	70K	700 80K 7.0	100K	mV e- μV/e-	Note 1
PRNU	Photo Response Non-Uniformity Peak-to-Peak		10		%V _{SAT}	
DSNU	Dark Signal Non-Uniformity Peak-to-Peak			1.0	mV	
DC	Dark Current	0.025	<1.0	2.0	nA/cm ²	Note 2
R	Responsivity		1.0		Vµj/cm²	
rms	Noise		5-20		e-	

Note 1: Maximum well capacity is achieved in Buried Channel Mode. Note 2: Values shown are for 25°C. Dark current doubles for every 5°-7°C.

Quantum Efficiency Enhancements

The CCD1600 CCD area arrays can be backside thinned for increased QE. The incident illumination enters through the backside of the array, and since no photons are absorbed in the polysilicon gate structures, the QE is increased. Also available are front side illuminated devices which can be coated with a fluorescent dye that absorbs UV light and fluoresces in the visible range. This provides CCD response at wavelengths less than 400nm.

Cosmetic Grading

Device grading helps to establish a ranking for the image quality that a CCD will provide. Blemishes are characterized as spurious pixels exceeding 10% of V_{SAT} with respect to neighboring elements. Blemish content is determined in the dark, at various illumination levels, and for different device temperatures.

The CCD1600 is available in various standard grades, as well as custom selected grades. Consult ANDANTA GmbH for available grading information and custom selections.

Warranty

Within twelve months of delivery to the end customer ANDANTA GmbH will repair or replace, at our option, any image sensor product if any part is found to be defective in materials or workmanship. Contact ANDANTA GmbH for assignment of warranty return number and shipping instructions to ensure prompt repair or replacement.

Certification

ANDANTA GmbH certifies that all products are carefully inspected and tested prior to shipment and will meet all of the specification requirements under which it is furnished

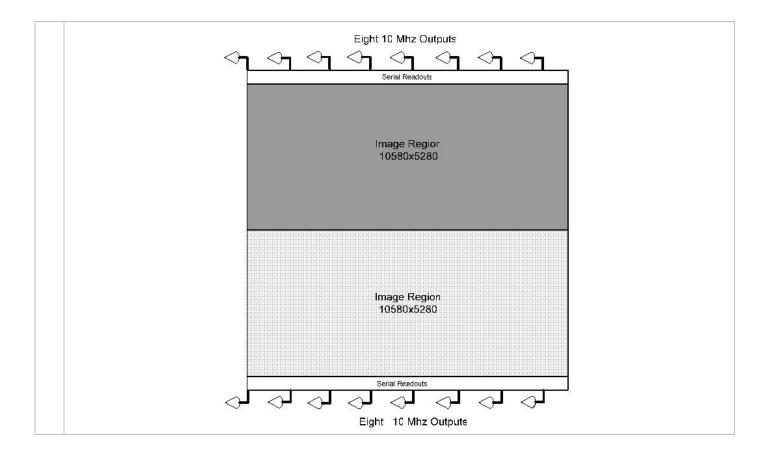
CCD1600 Image Sensor Pad Designation

Pad#	Label	Pad#	Label	Pad#
1	OS1	65	SUB	129
2	RG	66	OS6	130
3	SC	67	RG	131
4	RD	68	SC	132
5	SW	69	RD	133
6	OTG	70	SW	134
7	VLD	71	OTG	135
8	S3	72	VLD	136
9	S2	73	S3	137
10	S1	74	S2	138
11	RTN	75	S1	139
12	OD	76	RTN	140
13	SUB	77	OD	141
14	OS2	78	SUB	142
15	RG	79	OS7	143
16	SC	80	RG	144
17	RD	81	SC	145
18	SW	82	RD	146
19	OTG	83	SW	147
20	VLD	84	OTG	148
21	S3	85	VLD	149
22	S2	86	S3	150
23	S1	87	S2	151
24	RTN	88	S1	152
25	OD	89	RTN	153
26	SUB	90	OD	154
27	OS3	91	SUB	155
28	RG	92	OS8	156
29	SC	93	RG	157
30	RD	94	SC	158
31	SW	95	RD	159
32	OTG	96	SW	160
33	VLD	97	OTG	161
34	S3	98	VLD	162
35	S2	99	S3	163
36	S1	100	S2	164
37	RTN	101	S1	165
38	OD	102	RTN	166
39	SUB	103	OD	167
40	OS4	104	SUB	168
41	RG	105	BB	169
42	SC	106	SC	170
43	RD	107	A1	171
44	SW	108	A2	172
45	OTG	109	A3	173
46	VLD	110	SUB	174
47	S3	111	BB	175
48	S2	112	SC	176
49	S1	113	A1	177
50	RTN	114	A2	178
51	OD	115	A3	179
52	SUB	116	SUB	180
53	OS5	117	BB	181
54	RG	118	SC	182
55	SC	119	A1	183
56	RD	120	A2	184
57	SW	121	A3	185
58	OTG	122	SUB	186
59	VLD	123	BB	187
60	S3	124	SC	188
61	S2	125	A1	189
62	S1	126	A2	190
63	RTN	127	A3	191
64	OD	128	SUB	192

¥	Label	Pad#	
	BB	193	
ł	SC	194	
	A1	195	1
ŝ	A2	196	1
5 	A3	197	-
ŝ.			
8	SUB	198	_
	BB	199	
	SC	200	1
8	A1	201	
ŝ	A2	202	
-	A3	203	-
-		203	14
i.	SUB		
	BB	205	
i.	SC	206	
	A1	207	
ŝ	A2	208	
į.	A3	209	1
5	SUB	210	-
3 5	BB	210	
0 	1000 C		-
Ş	SC	212	
	A1	213	
	A2	214	1.2
	A3	215	1
ŝ	SUB	216	12
2	SUB	217	
ę.		217	-
8	OD	218	
1	RTN	219	
1	S1	220	
30	S2	221	
ŝ.	S3	222	
	VLD	223	-
-	OTG	223	1,5
ŝ.	Participation of the second se		
	SW	225	
	RD	226	ľ
	SC	227	Ĩ
ŝ	RG	228	
6	OS16	229	1,5
5	SUB	230	-
5		230	-
0	OD		_
2	RTN	232	
	S1	233	
	S2	233 234	1.2
	S3	235	1
ş	VLD	236	
2 4			
2	OTG	237	-
2	SW	238	
	RD SC	239	
	SC	240	
2	RG	241	
2	OS15	242	
9 9	SUB	242	-
3			-
	OD	244	
	RTN	245	
	S1	246	
j.	S2	247	
e	S3	248	-
2			
<u>ś</u>	VLD	249	1
ĝ.	OTG	250	
5	SW	251	
2	RD	252	1
ŝ.	SC	253	
i. Ş	RG	255	
i i	OS14	254	-
2			
	SUB	256	
_			-

#	Label	Pad#	Label
3	OD	257	SUB
, 	100 Perfection 1		A3
	RTN	258	
)	S1	259	A2
5	S2	260	A1
	S3	261	SC
3	VLD	262	BB
)	OTG	263	SUB
)	SW	264	A3
ĺ.	RD	265	A2
	SC	266	A1
2	RG	267	SC
<u> </u>	OS13		
1		268	BB
5	SUB	269	SUB
5	OD	270	A3
÷	RTN	271	A2
}	S1	272	A1
)	S2	273	SC
)	S3	274	BB
-	VLD	275	SUB
	OTG	276	A3
2	SW		A3 A2
		277	
ł	RD	278	A1
5	SC	279	SC
5	RG	280	BB
	OS12	281	SUB
3	SUB	282	A3
)	OD	283	A2
)	RTN	284	A1
<u> </u>	S1	285	SC
	S2	286	A0/06/2003
2			BB
	S3	287	SUB
ł	VLD	288	A3
5	OTG	289	A2
5	SW	290	A1
7	RD	291	SC
3	SC	292	BB
)	RG	293	SUB
)	OS11	294	A3
<u> </u>	SUB	295	A2
	E. SAMANA PROPERTY AND		
2	OD	296	A1
	RTN	297	SC
ł	S1	298	BB
5	S2	299	SUB
5 7 3 9	S3	300	A3
7	VLD	301	A2
3	OTG	302	A1
1	SW	303	SC
<u></u>			1755.77
	RD	304	BB
	SC		
2	RG		
3	OS10		
1	SUB		
5	OD		
3	RTN		
2	S1		
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3))	- 52 - S3		
, ,			
	VLD		
	OTG		
2	SW		
3	RD		
ŀ	SC		
5	RG		
2 3 4 5	OS9		

OS9



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